



Internal Use Only

Website: <http://biz.LGservice.com>

COLOR MONITOR SERVICE MANUAL

CHASSIS NO. : LM 84B

MODEL: **FLATRON** W1952TQ(W1952TQ-PFT.K***A**)

() **Same model for Service

CAUTION

BEFORE SERVICING THE UNIT,
READ THE SAFETY PRECAUTIONS IN THIS MANUAL.



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SPECIFICATIONS

1. LCD CHARACTERISTICS

Type	: TFT Color LCD Module
Active Display Area	: 19 inch diagonal
Pixel Pitch	: 0.285 (H) x 0.285 (V)
Size	: 493.7(H) x 320.1(V) x 16.5(D)
Color Depth	: 16.7M colors
Electrical Interface	: LVDS
Surface Treatment	: AG(Haze 25%), Hard Coating(3H)
Operating Mode	: Normally White
Backlight Unit	: 4 CCFL

2. OPTICAL CHARACTERISTICS

2-1. Viewing Angle by Contrast Ratio ≥ 5

Left : +80° min., +88°(Typ) Right : -80° min., -88°(Typ)
Top : +80° min., +85°(Typ) Bottom : -80° min., -85°(Typ)

2-2. Luminance : 180(Typ) (Typ. ± 30)-**sRGB**
: 210(min), 300(Typ)-**6500K**
: 150(min)-**9300K**

2-3. Contrast Ratio : 500(min), 1000(Typ)
DFC -> 10000 : 1 (Typ)

3. SIGNAL (Refer to the Timing Chart)

3-1. Sync Signal
• Type : Separate Sync, SOG, Digital

3-2. Video Input Signal

- 1) Type : R, G, B Analog
- 2) Voltage Level : 0~0.7 V
- 3) Input Impedance : 75 Ω

3-3. Operating Frequency

Horizontal : 28 ~ 83kHz
Vertical : 56 ~ 75Hz

4. MAX. RESOLUTION

Analog	: 1440 x 900@60Hz
Digital	: 1440 x 900@60Hz

5. POWER SUPPLY

5-1. Power Adaptor(Built-in Power)
Input : AC 100-240V~, 50/60Hz, 0.8A

5-2. Power Consumption

MODE	H/V SYNC	VIDEO	POWER CONSUMPTION	LED COLOR
POWER ON (NORMAL)	ON/ON	ACTIVE	less than 39 W(max)	BLUE
			less than 36 W(typ)	
STAND BY	OFF/ON	OFF	less than 1 W	AMBER
SUSPEND	ON/OFF	OFF	less than 1 W	AMBER
DPMS OFF	OFF/OFF	OFF	less than 1 W	AMBER
POWER S/W OFF	-	-	less than 1 W	OFF

6. ENVIRONMENT

6-1. Operating Temperature : 10°C~35°C (50°F~95°F)
6-2. Relative Humidity : 10%~80% (Non-condensing)
6-3. MTBF : 50,000 HRS with 90% Confidence level
Lamp Life : 40,000 Hours (Min)

7. DIMENSIONS (with TILT/SWIVEL)

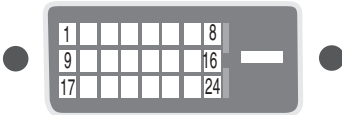
Width	: 451.5 mm (17.78")
Depth	: 386 mm (15.2")
Height	: 220 mm (8.66")

8. WEIGHT (with TILT/SWIVEL)

Net. Weight	: 3.9 kg (8.6 lbs)
Gross Weight	: 5.02 kg (11.07 lbs)

Signal Connector Pin Assignment

• DVI-D Connector (Digital)




Pin	Signal (DVI-D)
1	T. M. D. S. Data2-
2	T. M. D. S. Data2+
3	T. M. D. S. Data2/4 Shield
4	T. M. D. S. Data4-
5	T. M. D. S. Data4+
6	DDC Clock
7	DDC Data
8	Analog Vertical Sync.
9	T. M. D. S. Data1-
10	T. M. D. S. Data1+
11	T. M. D. S. Data1/3 Shield
12	T. M. D. S. Data3-
13	T. M. D. S. Data3+
14	+5V Power
15	Ground (return for +5V, H. Sync. and V. Sync.)

Pin	Signal (DVI-D)
16	Hot Plug Detect
17	T. M. D. S. Data0-
18	T. M. D. S. Data0+
19	T. M. D. S. Data0/5 Shield
20	T. M. D. S. Data5-
21	T. M. D. S. Data5+
22	T. M. D. S. Clock Shield
23	T. M. D. S. Clock+
24	T. M. D. S. Clock-

T. M. D. S. (Transition Minimized Differential Signaling)

PRECAUTION

WARNING FOR THE SAFETY-RELATED COMPONENT.

- There are some special components used in LCD monitor that are important for safety. **These parts are marked  on the schematic diagram and the replacement parts list.** It is essential that these critical parts should be replaced with the manufacturer's specified parts to prevent electric shock, fire or other hazard.
- Do not modify original design without obtaining written permission from manufacturer or you will void the original parts and labor guarantee.

TAKE CARE DURING HANDLING THE LCD MODULE WITH BACKLIGHT UNIT.

- Must mount the module using mounting holes arranged in four corners.
- Do not press on the panel, edge of the frame strongly or electric shock as this will result in damage to the screen.
- Do not scratch or press on the panel with any sharp objects, such as pencil or pen as this may result in damage to the panel.
- Protect the module from the ESD as it may damage the electronic circuit (C-MOS).
- Make certain that treatment person's body are grounded through wrist band.
- Do not leave the module in high temperature and in areas of high humidity for a long time.
- The module not be exposed to the direct sunlight.
- Avoid contact with water as it may a short circuit within the module.
- If the surface of panel become dirty, please wipe it off with a softmaterial. (Cleaning with a dirty or rough cloth may damage the panel.)

CAUTION

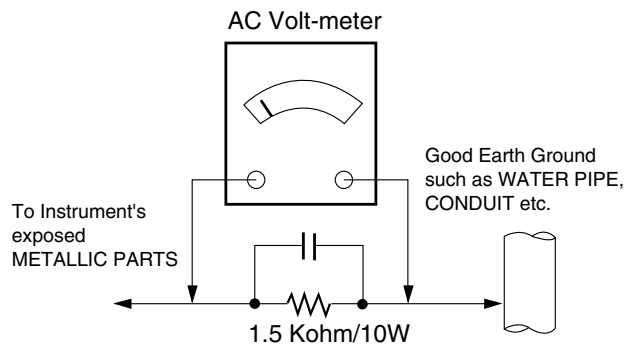
Please use only a plastic screwdriver to protect yourself from shock hazard during service operation.

WARNING

BE CAREFUL ELECTRIC SHOCK !

- If you want to replace with the new backlight (CCFL) or inverter circuit, must disconnect the AC adapter because high voltage appears at inverter circuit about 650Vrms.
- Handle with care wires or connectors of the inverter circuit. If the wires are pressed cause short and may burn or take fire.

Leakage Current Hot Check Circuit



SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the **SAFETY PRECAUTIONS** on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
 - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
 - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.

CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.

- d. Discharging the picture tube anode.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe.
Do not test high voltage by "drawing an arc".
 3. Discharge the picture tube anode only by (a) first connecting one end of an insulated clip lead to the degaussing or kine aquadag grounding system shield at the point where the picture tube socket ground lead is connected, and then (b) touch the other end of the insulated clip lead to the picture tube anode button, using an insulating handle to avoid personal contact with high voltage.
 4. Do not spray chemicals on or near this receiver or any of its assemblies.
 5. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)
CAUTION: This is a flammable mixture.
Unless specified otherwise in this service manual, lubrication of contacts is not required.
 6. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
 7. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
 8. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
Always remove the test receiver ground lead last.

9. Use with this receiver only the test fixtures specified in this service manual.

CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called *Electrostatically Sensitive (ES) Devices*. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range of 500°F to 600°F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a small wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle.

Do not use freon-propelled spray-on cleaners.

5. Use the following unsoldering technique
 - a. Allow the soldering iron tip to reach normal temperature.
(500°F to 600°F)
 - b. Heat the component lead until the solder melts.
 - c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.

CAUTION: Work quickly to avoid overheating the circuitboard printed foil.

6. Use the following soldering technique.
 - a. Allow the soldering iron tip to reach a normal temperature (500°F to 600°F)
 - b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
 - c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.

CAUTION: Work quickly to avoid overheating the circuit board printed foil.

- d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor

Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device

Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. Carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

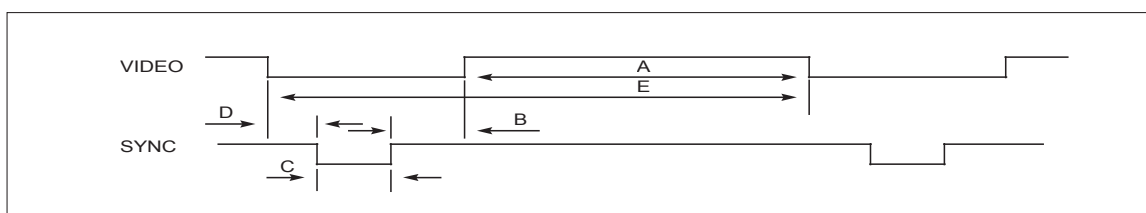
At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife.
Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.
Carefully crimp and solder the connections.

CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

TIMING CHART



mode	section	polarity	DOT CLOCK [MHz]	Frequency [kHz]/[Hz]	Total Period (E)	Display (A)	Front Porch(D)	Sync. (C)	Back Porch(B)	Resolution
1	H(Pixels)	+	25.175	31.469	800	640	16	96	48	640 x 350
	V(Lines)	-		70.09	449	350	37	2	60	
2	H(Pixels)	-	28.321	31.468	900	720	18	108	54	720 x 400
	V(Lines)	+		70.08	449	400	12	2	35	
3	H(Pixels)	-	25.175	31.469	800	640	16	96	48	640 x 480
	V(Lines)	-		59.94	525	480	10	2	33	
4	H(Pixels)	-	31.5	37.5	840	640	16	64	120	640 x 480
	V(Lines)	-		75	500	480	1	3	16	
5	H(Pixels)	+	40.0	37.879	1056	800	40	128	88	800 x 600
	V(Lines)	+		60.317	628	600	1	4	23	
6	H(Pixels)	+	49.5	46.875	1056	800	16	80	160	800 x 600
	V(Lines)	+		75.0	625	600	1	3	21	
7	H(Pixels)	+/-	57.283	49.725	1152	832	32	64	224	832 x 624
	V(Lines)	+/-		74.55	667	624	1	3	39	
8	H(Pixels)	-	65.0	48.363	1344	1024	24	136	160	1024 x 768
	V(Lines)	-		60.0	806	768	3	6	29	
9	H(Pixels)	-	78.75	60.123	1312	1024	16	96	176	1024 x 768
	V(Lines)	-		75.029	800	768	1	3	28	
10	H(Pixels)	+/-	100.0	68.681	1456	1152	32	128	144	1152 x 870
	V(Lines)	+/-		75.062	915	870	3	3	39	
11	H(Pixels)	+/-	92.978	61.805	1504	1152	18	134	200	1152 x 900
	V(Lines)	+/-		65.96	937	900	2	4	31	
12	H(Pixels)	+	108.0	63.981	1688	1280	48	112	248	1280 x 1024
	V(Lines)	+		60.02	1066	1024	1	3	38	
13	H(Pixels)	+	135.0	79.976	1688	1280	16	144	248	1280 x 1024
	V(Lines)	+		75.035	1066	1024	1	3	38	
14	H(Pixels)	+	88.750	55.5	1600	1440	48	32	80	1440 x 900
	V(Lines)	-		59.90	926	900	3	6	17	
15	H(Pixels)	-	106.500	55.935	1904	1440	80	152	232	1440x 900
	V(Lines)	+		59.887	934	900	3	6	25	
16	H(Pixels)	-	136.750	70.635	1936	1440	96	152	248	1440x 900
	V(Lines)	+		74.984	942	900	3	6	33	

DISASSEMBLY

1. Put a cushion or soft cloth on a flat surface.
2. Place the monitor face down on the cushion or soft cloth.



3. Slide the Cable Deco Cover out from the stand body.



4. Press the hook, Take off the stand base from stand body.



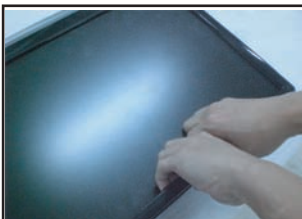
5. Please pull the stand body lightly to separate it from the hinge body.



6. Remove the screws.



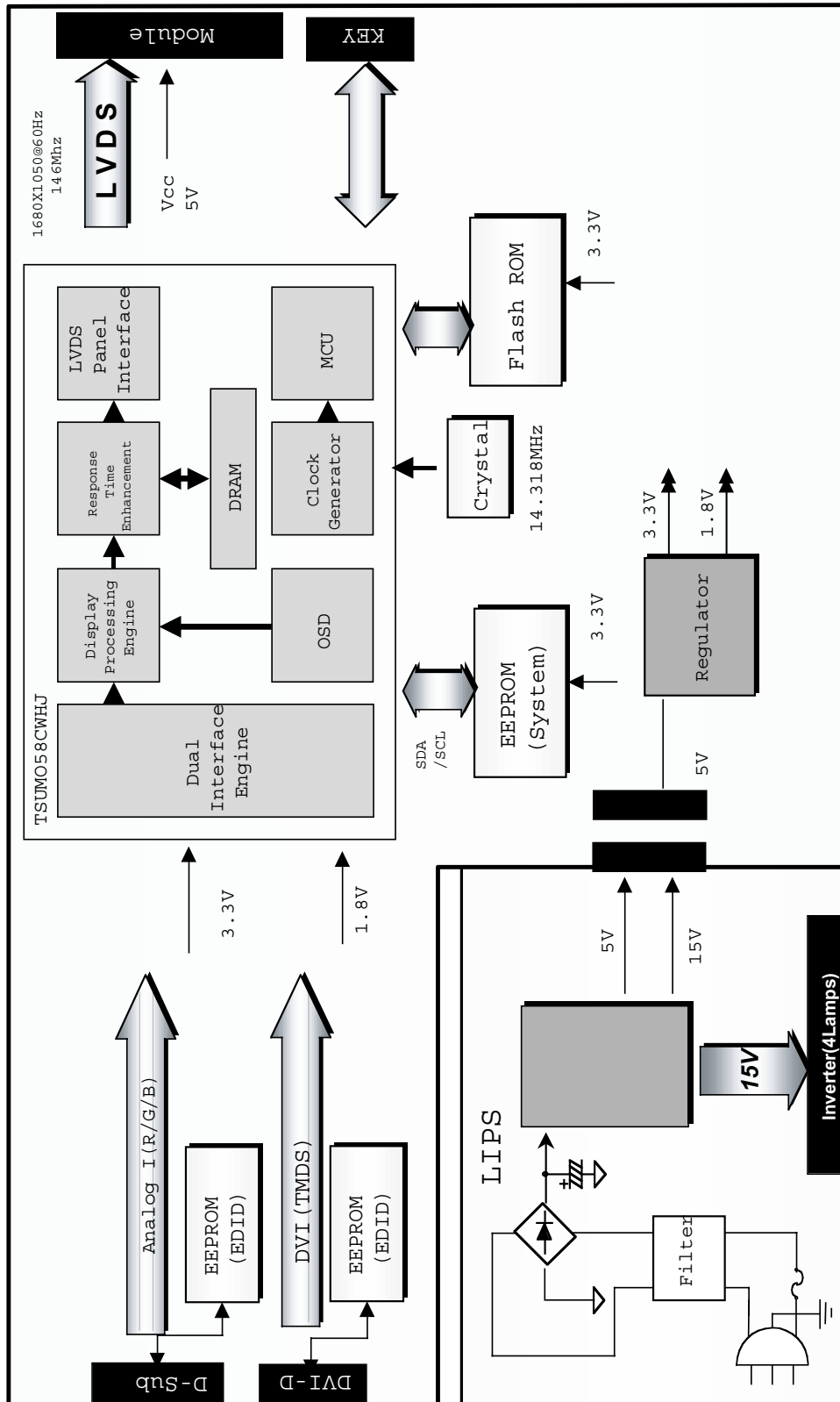
7. Pull the front cover upward, then separate all the latches.



8. Place the monitor face down, then disassemble back cover.



BLOCK DIAGRAM



DESCRIPTION OF BLOCK DIAGRAM

1. Video Controller Part.

This part amplifies the level of video signal for the digital conversion and converts from the analog video signal to the digital video signal using a pixel clock.

The pixel clock for each mode is generated by the PLL.

The range of the pixel clock is 136MHz In W1952TQ.

This part consists of the Scaler, ADC convertor, TMDS receiver and LVDS transmitter.

The Scaler gets the video signal converted analog to digital, interpolates input to 1440X900(W1952TQ) resolution signal and outputs 8-bit R, G, B signal to transmitter.

2. Power Part.

This part consists of the one 3.3V, and one 1.8V regulators to convert power which is provided 5V in Power board. 15V is provided for inverter in W1952TQ.

Also, 5V is converted 3.3V and 1.8V by regulator. Converted power is provided for IC in the main board.

The inverter converts from DC 15V to AC 700Vrms and operates back-light lamps of module in W1952TQ.

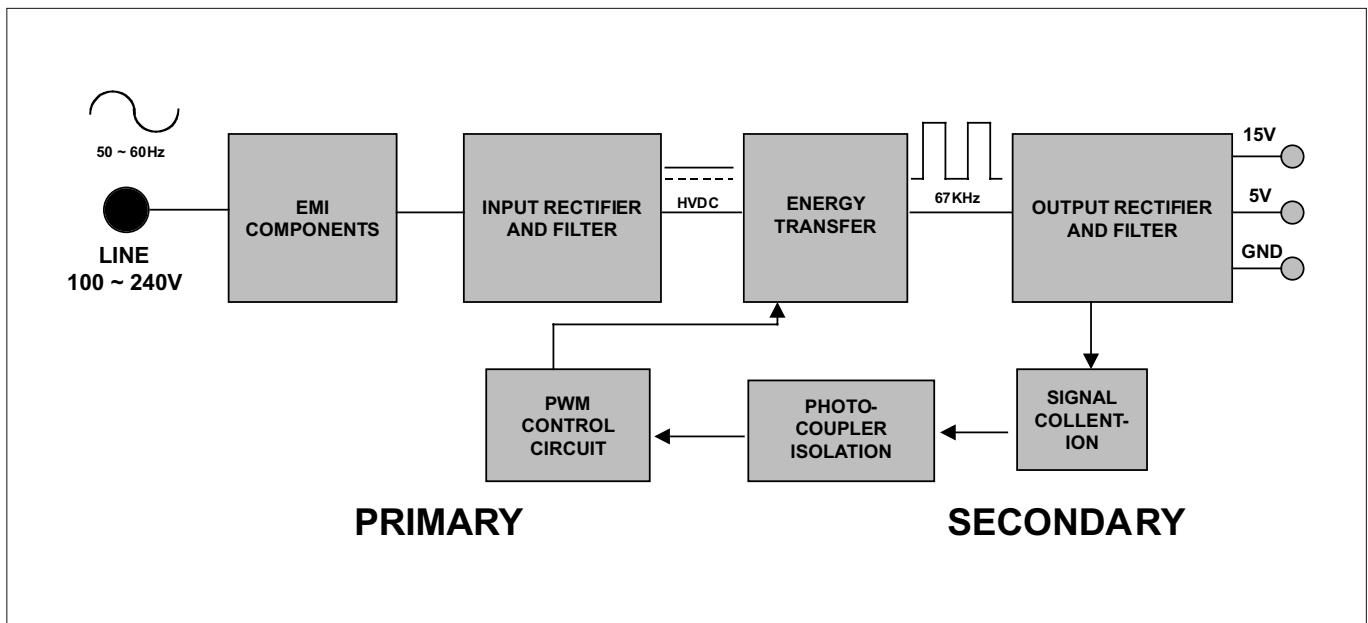
3. MICOM Part.

This part is include video controller part. And this part consists of EEPROM IC , control data, Reset IC and the Micom.

The Micom distinguishes polarity and frequency of the H/V sync are supplied from signal cable.

The controlled data of each modes is stored in EEPROM.

LIPS Board Block Diagram



Operation description_Power

1. EMI components.

This part contains of EMI components to comply with global marketing EMI standards like FCC,VCCI CISPR, the circuit included a line-filter, across line capacitor and of course the primary protection fuse.

2. Input rectifier and filter.

This part function is for transfer the input AC voltage to a DC voltage through a bridge rectifier and a bulk capacitor.

3. Energy Transfer.

This part function is for transfer the primary energy to secondary through a power transformer.

4. Output rectifier and filter.

This part function is to make a pulse width modulation control and to provide the driver signal to power switch, to adjust the duty cycle during different AC input and output loading condition to achieve the dc output stabilized, and also the over power protection is also monitor by this part.

5. Photo-Coupler isolation.

This part function is to feed back the DC output changing status through a photo transistor to primary controller to achieve the stabilized DC output voltage.

6. Signal collection.

This part function is to collect the any change from the DC output and feed back to the primary through photo transistor.

ADJUSTMENT

Windows EDID V1.0 User Manual

Operating System: MS Windows 98, 2000, XP

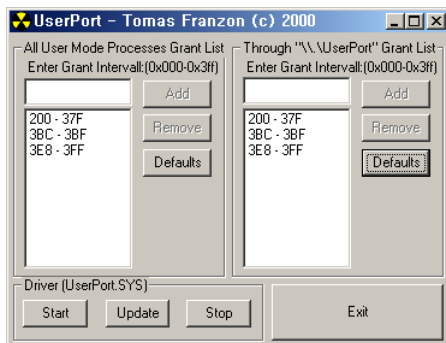
Port Setup: Windows 98 => Doesn't need setup

Windows 2000, XP => Need to Port Setup.

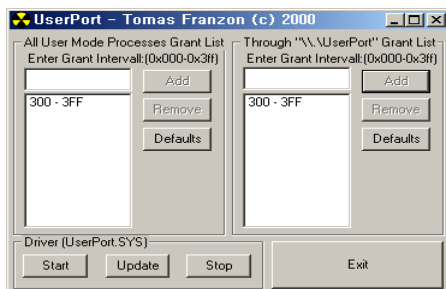
This program is available for LCD Monitor only.

1. Port Setup

- Copy "UserPort.sys" file to
"c:\WINNT\system32\drivers" folder
- Run Userport.exe



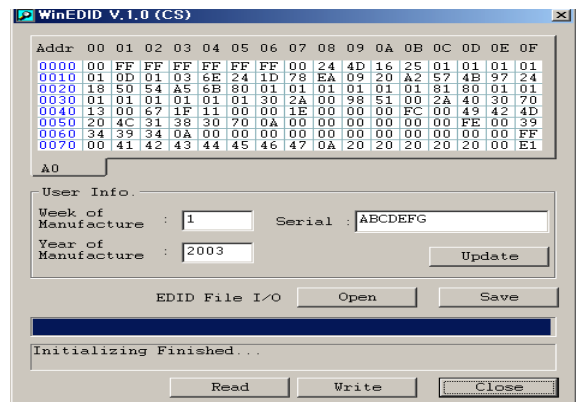
- Remove all default number
- Add 300-3FF



- Click Start button.
- Click Exit button.

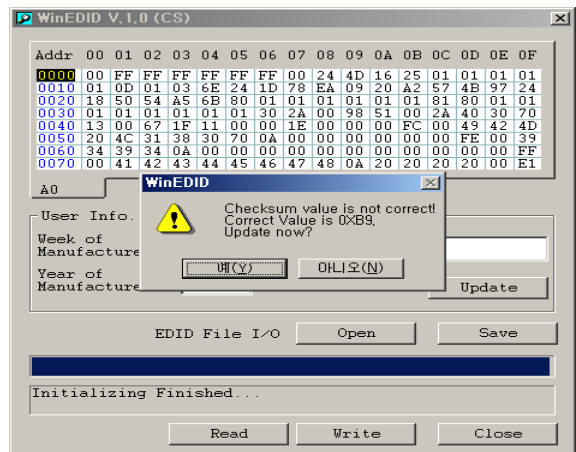
2. EDID Read & Write

1) Run WinEDID.exe



2) Edit Week of Manufacture, Year of Manufacture, Serial Number

- Input User Info Data
- Click "Update" button
- Click "Write" button



SERVICE OSD

- 1) Turn off the power switch at the right side of the display.
- 2) Wait for about 5 seconds and press MENU, POWER switch for 1 second interval.
- 3) The SVC OSD menu contains additional menus that the User OSD menu as described below.
 - a) CLEAR ETI : To initialize using time.
 - c) Auto Color : W/B balance and Automatically sets the gain and offset value.
(press key for over 3 sec)
 - d) AGING : Select Aging mode(on/off).
 - b) Module : To select applied module.
 - d) NVRAM INIT : EEPROM initialize.(24C16, press key for over 3 sec)
 - e) R/G/B-9300K : Allows you to set the R/G/B-9300K value manually.
 - f) R/G/B-6500K : Allows you to set the R/G/B-6500K value manually.
 - g) R/G/B-Offset : Allows you to set the R/G/B-Offset value manually.(Analog Only)
 - h) R/G/B-Gain : Allows you to set the R/G/B-Gain value manually.(Analog Only)

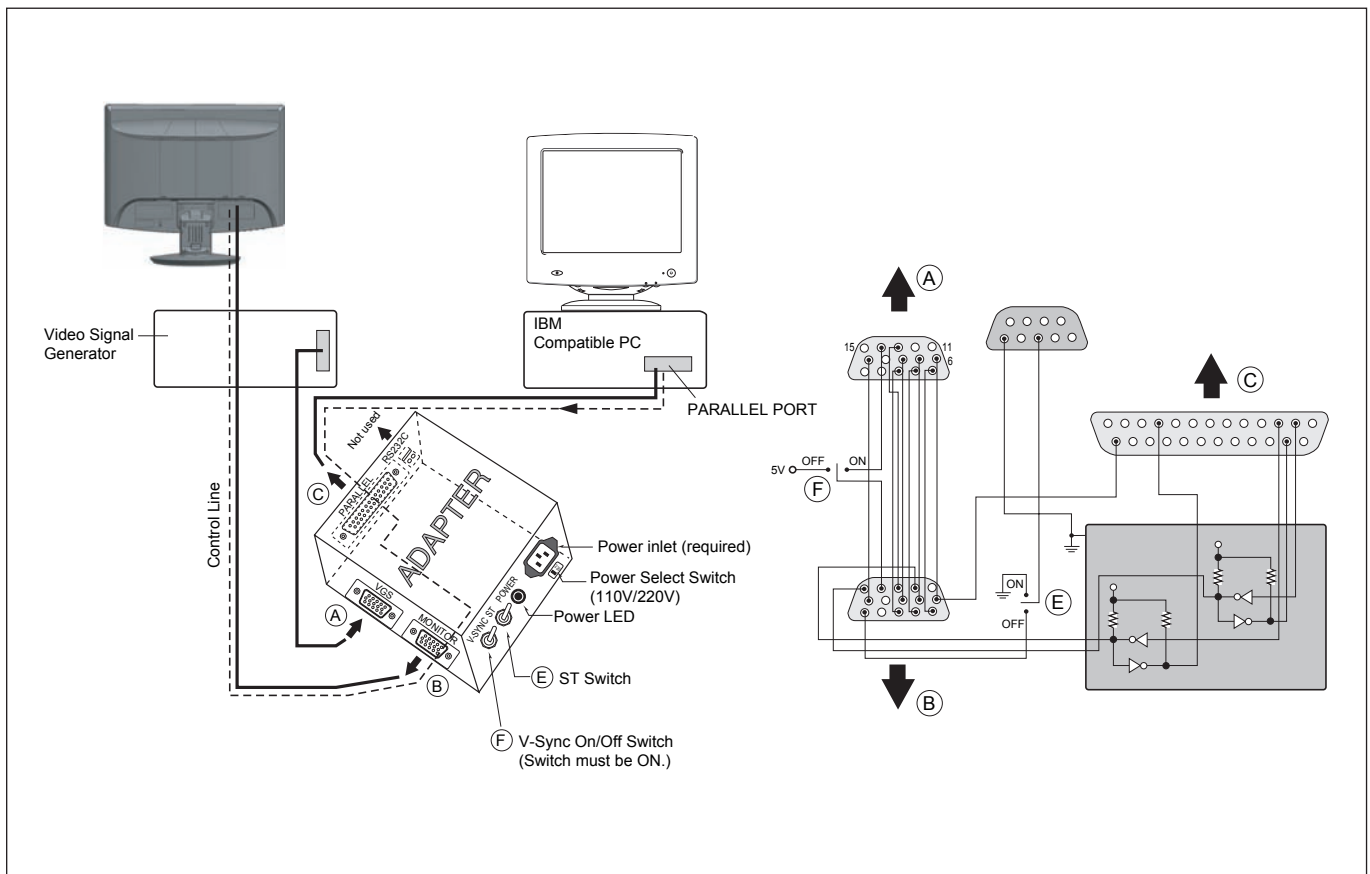
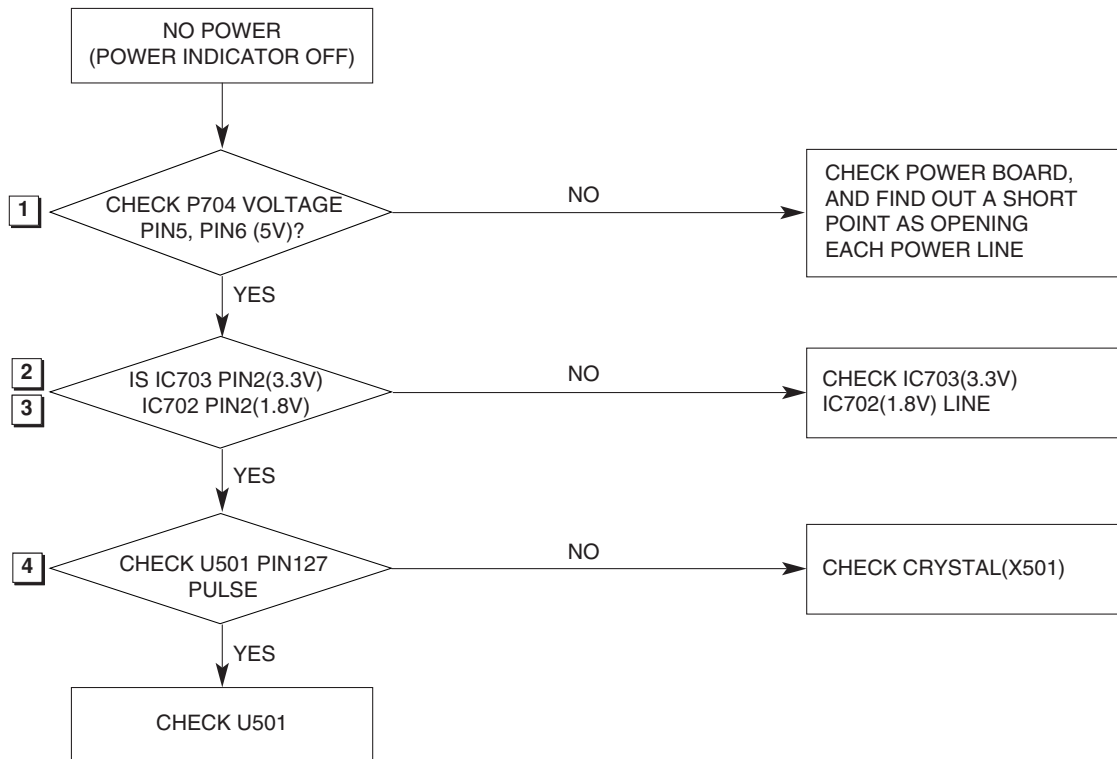


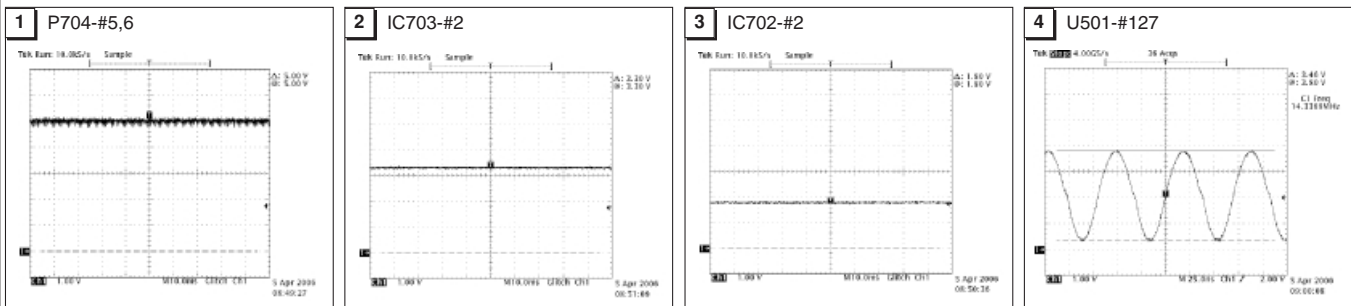
Figure 1. Cable Connection

TROUBLESHOOTING GUIDE

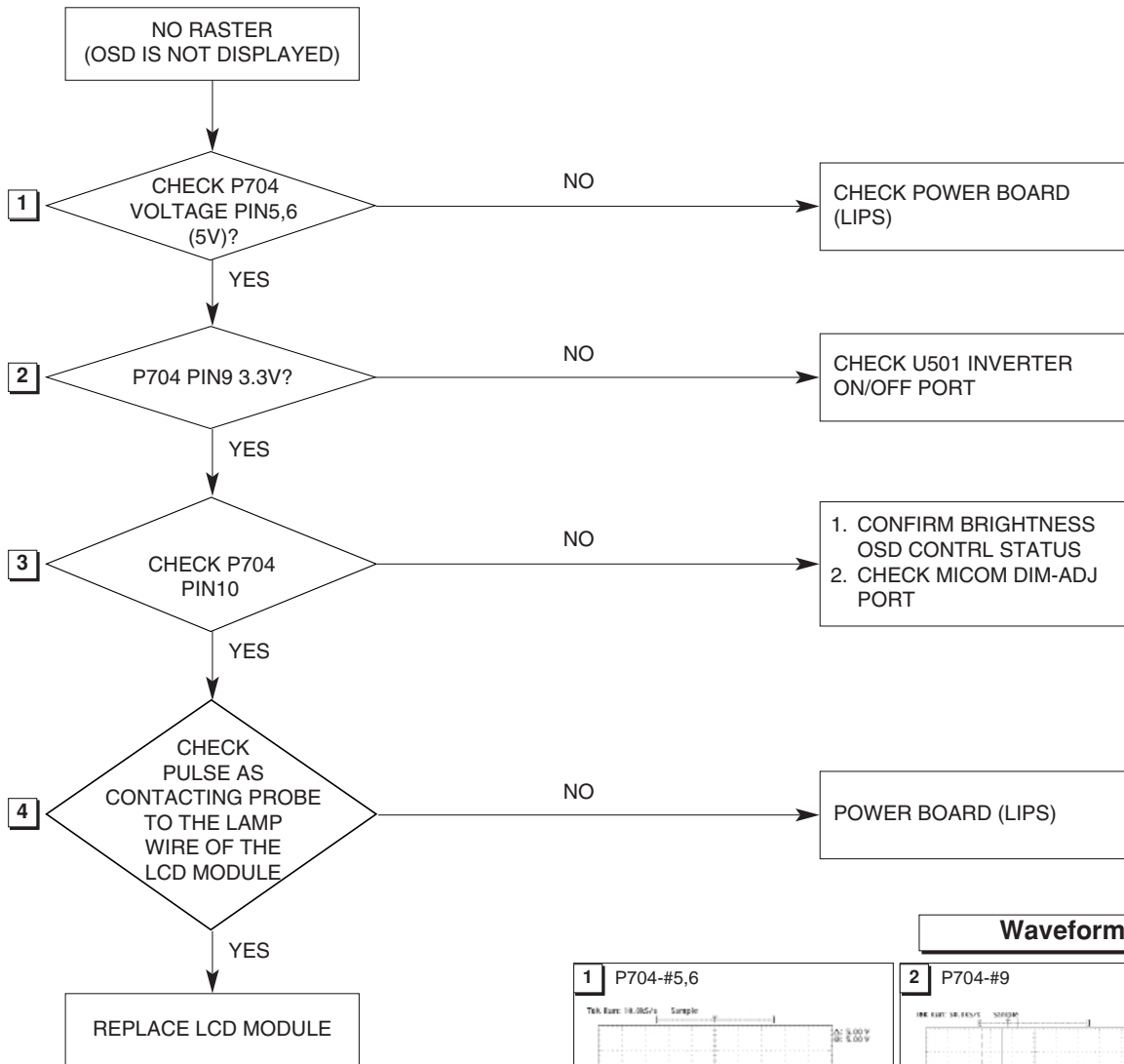
1. NO POWER



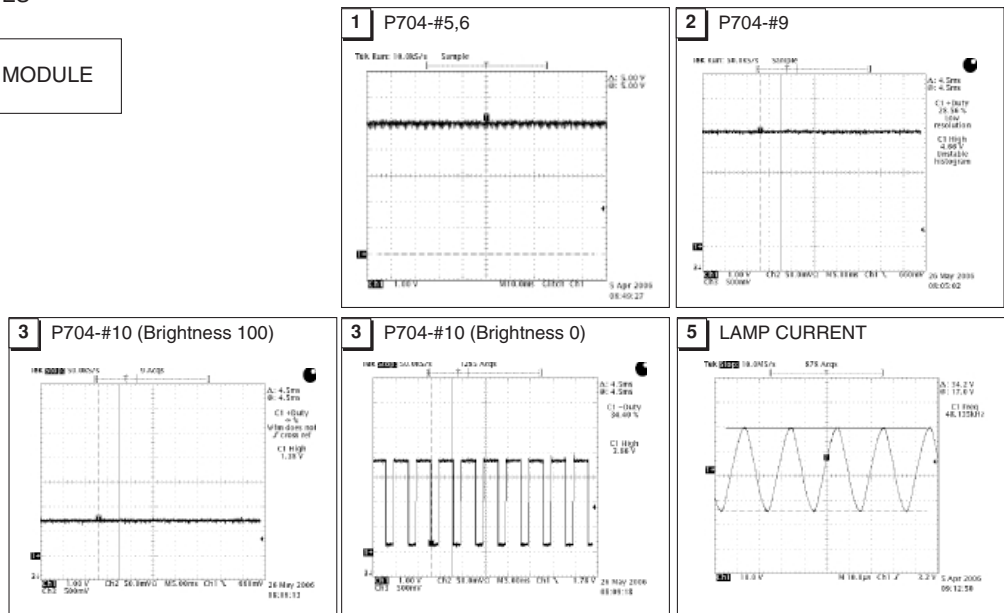
Waveforms



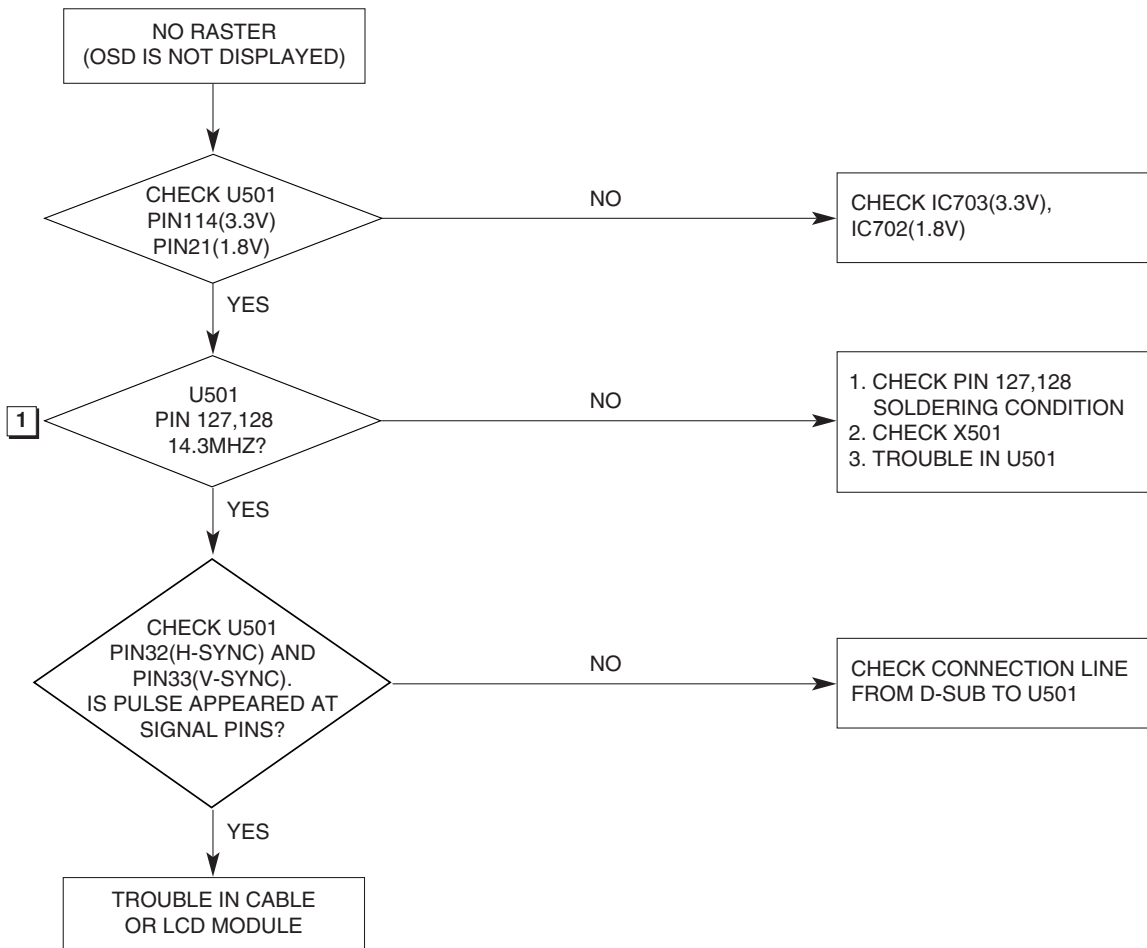
2. NO RASTER (OSD IS NOT DISPLAYED) – LIPS



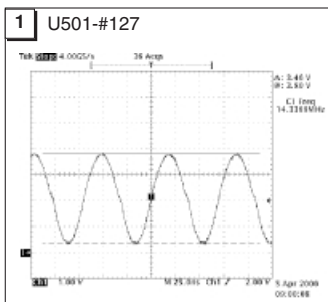
Waveforms



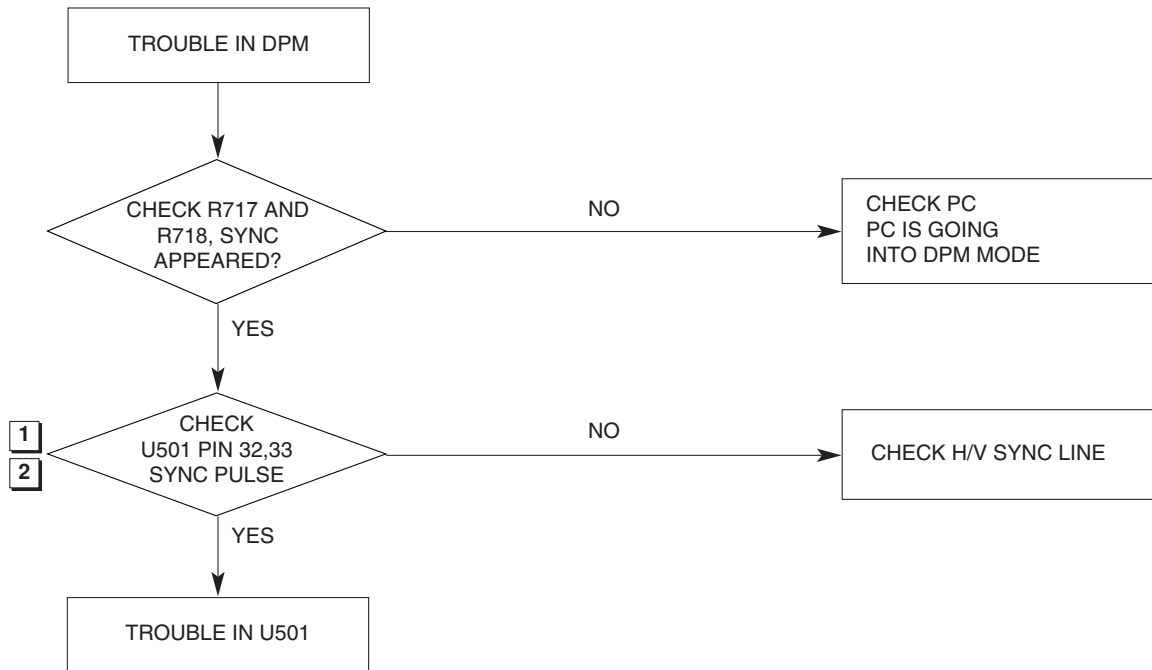
3. NO RASTER (OSD IS NOT DISPLAYED) - MAIN



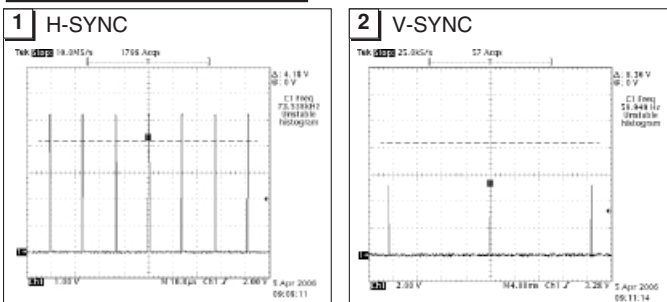
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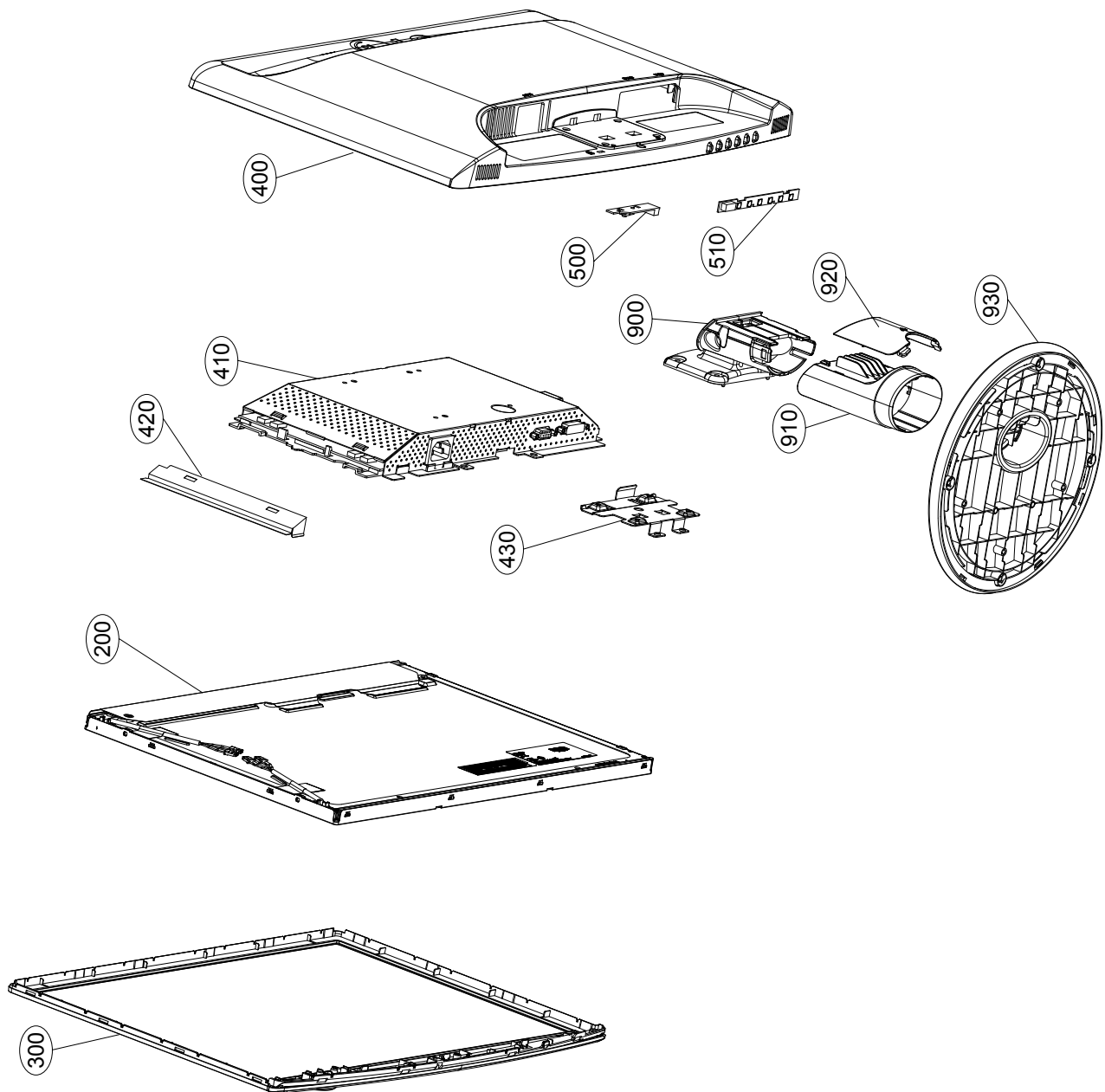
4. TROUBLE IN DPM



Waveforms



EXPLODED VIEW



EXPLODED VIEW PARTS LIST

Ref. No.	Part No.	Description
200	EAJ35661001	LCD,Module-TFT,HT190WG1-100 ZBD DRIVER 19.0INCH 1440X900 300CD COLOR 72% 16/9 700:1 4CCFL, 160/160, 5ms BOE HYDIS TECHNOLOGY
	EAJ36290802	LCD,Module-TFT,LM190WX1-TLC2 DRIVER 19INCH 1440X900 300CD COLOR 72% 16/10 850:1 P7, 5ms,Non-ZBD,MAGNA source D-IC, OKI gate D-IC, TLI T-con, 160/160 LG PHILIPS LCD
	EAJ42097502	LCD,Module-TFT,M190A1-L07 Non-ZBD WXGA 19INCH 1440X900 380CD COLOR 72% 16/10 1000:1 CMO 19"W WXGA+,Non-ZBD,Non-Glare, TN, 16.7M, Response time:5ms,Viewing angle:170/
	EAJ32175201	LCD,Module-TFT,M190PW01-V0 DRIVER 19INCH 1440X900 300CD COLOR 72% 16/10 800:1 5MS, 2CH-LVDS, 160/160, 4LAMP, NON-ZBD AU OPTRONICS CORP
	EAJ38022802	LCD,Module-TFT,M190MWW1 Non-ZBD WXGA 19INCH 1440X900 300CD COLOR 72% 16/10 800:1 5ms, 16.2M, TN,160/160(CR=10), For Only China domestic market SVA MTD
	EAJ41390301	SVA190WX02TB WXGA 19INCH 1440X900 300CD COLOR 72% 16/10 800:1 SVA-NEC 19"W WXGA+,ZBD,Color Gamut 16.77M,6bit+HiFRC,Response time 5ms,LVDS 2port,Viewin
300	ABJ35702302	Cabinet Assembly,W1952 S 19" CABINET ASSY FOR LPL/CMO/MTD
	ABJ35702304	Cabinet Assembly,W1952 S 19" CABINET ASSY, 02 CKD
	ABJ36830002	Cabinet Assembly,W1952 CABINET ASSY FOR AUO/BOE/NEC/CMO+
400	ACQ35704405	Cover Assembly,Rear,W1952 S 19" W1952 BACKCOVER
	ACQ35704407	Cover Assembly,Rear,W1952 S 19" W1952 BACKCOVER
410	AGF35751203	Package Assembly,MAIN W52 series ODC Mstar
420	MGJ41193201	Plate,Shield,PRESS SPTE 0.3 SHIELD SPTE 0.3T, Lamp Shield, L1755/W1952/W2252
	MGJ41193202	Plate,Shield,PRESS SPTE 0.3 SHIELD SPTE 0.3T, Lamp Shield, L1755/W1952/W2252
430	MGJ41204901	Plate,Metal,PRESS SBHG 0.8T SUPPORTER EGI W1952 METAL SUPPORT EGI 0.8T
	MGJ41204902	Plate,Metal,PRESS SBHG 0.8T SUPPORTER EGI W1952 METAL SUPPORT EGI 0.8T
	MGJ41204903	Plate,Metal,PRESS SBHG 0.8T SUPPORTER EGI W1952 METAL SUPPORT EGI 0.8T
500	EBR42021801	PCB Assembly,LED & P/SW T.T LM84 W52 series - -
510	EBR41684101	PCB Assembly,CONTROL T.T LM84A W52 series RD -
900	ACQ33707101	Cover Assembly,L1954T LM57B 19" Cover, Hinge Assy, Normal Stand, L1954T
	ACQ33707107	Cover Assembly,L1954T,L207W LM57B 20" Cover, Hinge Assy Normal Stand, 01-CKD
910	MCK41193001	Cover,MOLD ABS L1755/WX52 ABS HF 350, Stand Body(L1755/WX52)
	MCK41193003	Cover,MOLD ABS L1755/WX52 ABS HF 350, Stand Body(L1755/WX52) BLACK CKD
920	MCK41193101	Cover,MOLD ABS L1755/WX52 ABS HF 350, Cover Cable
	MCK41193103	Cover,MOLD ABS L1755/WX52 ABS HF 350, Cover Cable Black CKD
930	AAN35706801	Base Assembly,STAND W1952, W2252 - W1952, W2252 stand base assy
	AAN35706802	Base Assembly,STAND W1952, W2252 - W1952, W2252 stand base assy

REPLACEMENT PARTS LIST

DATE:2007.11.20

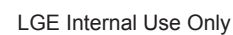
LOC NO.	PART NO.	DESCRIPTION/SPECIFICATON
CAPACITORS		
C501	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C502	0CK473CH56A	"Capacitor,Ceramic,Chip,C1608X7R1E473KT 47nF"
C503	0CK473CH56A	"Capacitor,Ceramic,Chip,C1608X7R1E473KT 47nF"
C504	0CK473CH56A	"Capacitor,Ceramic,Chip,C1608X7R1E473KT 47nF"
C505	0CK473CH56A	"Capacitor,Ceramic,Chip,C1608X7R1E473KT 47nF"
C506	0CC102CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H102JT 1nF"
C507	0CK473CH56A	"Capacitor,Ceramic,Chip,C1608X7R1E473KT 47nF"
C508	0CK473CH56A	"Capacitor,Ceramic,Chip,C1608X7R1E473KT 47nF"
C509	0CC270CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H270JT 27pF"
C510	0CC270CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H270JT 27pF"
C511	0CK103CK51A	"Capacitor,Ceramic,Chip,0603B103K500CT 10nF"
C512	0CK103CK51A	"Capacitor,Ceramic,Chip,0603B103K500CT 10nF"
C513	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C514	0CK224CF56A	"Capacitor,Ceramic,Chip,0603B224K160CT 220nF"
C515	0CK106CF638	"Capacitor,AL,Radial,SHL5.0TP16VB10M 10uF"
C516	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C517	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C518	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C519	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C520	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C521	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C522	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C523	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C524	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C525	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C526	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C527	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C528	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C529	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C530	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C531	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C532	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
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C535	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C536	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C537	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C538	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C539	0CC080CK11A	"Capacitor,Ceramic,Chip,C1608C0G1H080DT 8pF"
C540	0CC080CK11A	"Capacitor,Ceramic,Chip,C1608C0G1H080DT 8pF"
C541	0CC080CK11A	"Capacitor,Ceramic,Chip,C1608C0G1H080DT 8pF"
C700	0CC101CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H101JT 100p"
C701	0CC101CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H101JT 100p"
C702	0CC680CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H680JT 68pF"
C703	0CK104CK56A	"Capacitor,Ceramic,Chip,0603B104K500CT 100nF"
C704	0CC680CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H680JT 68pF"
C705	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C706	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C707	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C708	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C709	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C710	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C711	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C712	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C713	0CC680CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H680JT 68pF"
C714	0CC680CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H680JT 68pF"
C715	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C716	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C717	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C719	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C720	0CK475CC94A	"Capacitor,Ceramic,Chip,C1608Y5V0J475ZT 4.7u"
C722	0CK103CK51A	"Capacitor,Ceramic,Chip,0603B103K500CT 10nF"
C723	0CE107EF610	"Capacitor,AL,Radial,KMG16VB100M 100uF 20"
C725	0CE107EF610	"Capacitor,AL,Radial,KMG16VB100M 100uF 20"

LOC NO.	PART NO.	DESCRIPTION/SPECIFICATON
C726	0CE107EF610	"Capacitor,AL,Radial,KMG16VB100M 100uF 20"
C727	0CE107EF610	"Capacitor,AL,Radial,KMG16VB100M 100uF 20"
C728	0CK105CD56A	"Capacitor,Ceramic,Chip,C1608X7R1A105KT 1uF"
C729	0CK105CD56A	"Capacitor,Ceramic,Chip,C1608X7R1A105KT 1uF"
C730	0CK105CD56A	"Capacitor,Ceramic,Chip,C1608X7R1A105KT 1uF"
C731	0CK102CK56A	"Capacitor,Ceramic,Chip,0603B102K500CT 1nF 1"
C732	0CK102CK56A	"Capacitor,Ceramic,Chip,0603B102K500CT 1nF 1"
C733	0CK102CK56A	"Capacitor,Ceramic,Chip,0603B102K500CT 1nF 1"
C734	0CE107EF610	"Capacitor,AL,Radial,KMG16VB100M 100uF 20"
C738	0CK104CF56A	"Capacitor,Ceramic,Chip,0603B104K160CT 100nF"
C739	0CK105CD56A	"Capacitor,Ceramic,Chip,C1608X7R1A105KT 1uF"
C740	0CC101CK41A	"Capacitor,Ceramic,Chip,C1608C0G1H101JT 100p"
C780	0CE106CF638	"Capacitor,AL,Radial,SHL5.0TP16VB10M 10uF"
DIODES		
D700	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D701	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D702	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D703	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D704	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D705	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D706	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D707	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D708	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D709	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D710	0DSIH00018A	"Diode,Switching,ENKMC2837-T112 1.2V"
D711	0DSO00138A	"Diode,Schottky,MMBD301LT1G 600MV 30"
D712	0DD184009AA	"Diode Assembly,KDS184 KDS184 TP KEC"
ZD10	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD700	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD701	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD702	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD703	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD704	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD707	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD708	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD709	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ZD9	0DZ560009GB	"Diode,Zener,BZT52C5V6S-(F) 5.6V"
ICs		
IC700	0IMMR00014A	"IC,EEPROM,M24C02-RMN6TP 2KBIT"
IC702	0IPMG78403A	"IC,LDO Voltage Regulator,AZ1086S-1.8TRE1 3.2T"
IC703	0IPMGA0010A	"IC,LDO Voltage Regulator,AZ1117H-3.3 4.75TO10"
U501	0IPRP00784C	"IC,Video Processors,FE253MOH-LF 300MVT03"
U502	0EAN37157001	"IC,Serial Flash Memory,W25X20VSNIG 2MBIT 25"
U503	0IMMRSG036B	"IC,EEPROM,M24C16-WMN6TP 16KBIT"
FILTERS		
L700	0LCML00003B	"Filter,Bead,MLB-201209-0120P-N2"
L701	0LCML00003B	"Filter,Bead,MLB-201209-0120P-N2"
L702	0LCML00003B	"Filter,Bead,MLB-201209-0120P-N2"
TRANSISTORS		
Q501	0TRKE80046A	"TR,Bipolar,2N3904S NPN 6V 60V 4"
Q700	0TRKE80046A	"TR,Bipolar,2N3904S NPN 6V 60V 4"
Q701	0EBK39150701	"TR,Bipolar,KTA1241 PNP -8V -35V"
Q705	0TRKE80046A	"TR,Bipolar,2N3904S NPN 6V 60V 4"
Q706	0TR390609DC	"TR,Bipolar,2N3906S-RTK PNP -5V"
Q707	0TR390609DC	"TR,Bipolar,2N3906S-RTK PNP -5V"
Q760	0TR390609DC	"TR,Bipolar,2N3906S-RTK PNP -5V"
Q761	0TRKE80046A	"TR,Bipolar,2N3904S NPN 6V 60V 4"
RESISTORS		
R1	0RJ1602D677	"Resistor,Chip,MCR03EZPJ163 16KOHM"
R2	0RJ1602D677	"Resistor,Chip,MCR03EZPJ163 16KOHM"
R3	0RJ1801D677	"Resistor,Chip,MCR03EZPJ182 1.8KOHM"

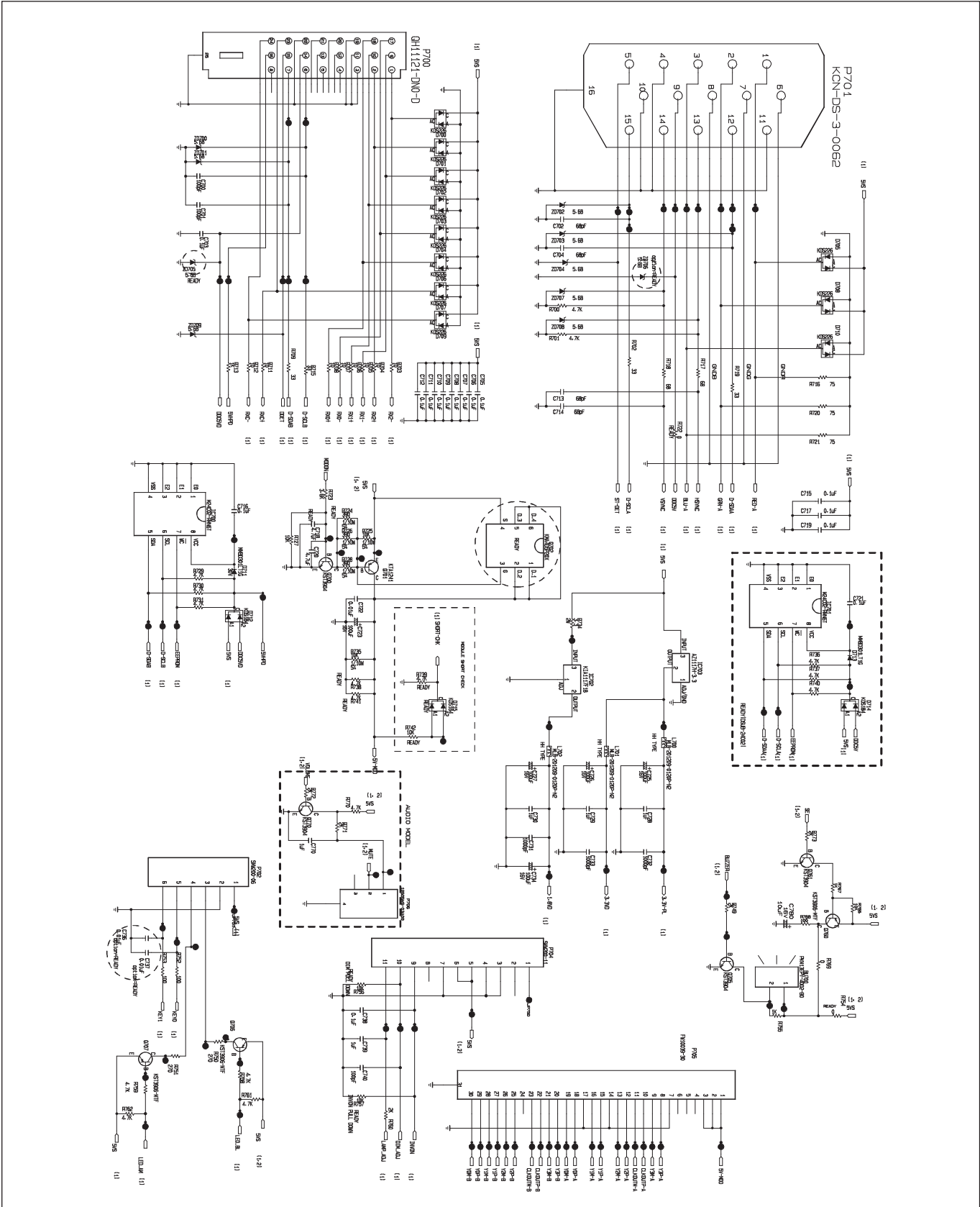
LOC NO.	PART NO.	DESCRIPTION/SPECIFICATON
R4	0RJ1801D677	"Resistor,Chip,MCR03EZPJ182 1.8KOHM"
R5	0RJ2201D677	"Resistor,Chip,MCR03EZPJ222 2.2KOHM"
R501	0RJ1000D677	"Resistor,Chip,MCR03EZPJ101 100OHM"
R502	0RJ0562D677	"Resistor,Chip,MCR03EZPJ560 56OHM 5"
R503	0RJ1000D677	"Resistor,Chip,MCR03EZPJ101 100OHM"
R504	0RJ0562D677	"Resistor,Chip,MCR03EZPJ560 56OHM 5"
R505	0RJ4700D677	"Resistor,Chip,MCR03EZPJ471 470OHM"
R506	0RJ1000D677	"Resistor,Chip,MCR03EZPJ101 100OHM"
R507	0RJ0562D677	"Resistor,Chip,MCR03EZPJ560 56OHM 5"
R508	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R509	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R510	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R511	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R512	0RJ4700D677	"Resistor,Chip,MCR03EZPJ471 470OHM"
R513	0RJ4700D677	"Resistor,Chip,MCR03EZPJ471 470OHM"
R514	0RJ0000D677	"Resistor,Chip,MCR03EZPJ000 0OHM 5%"
R516	0RJ3900D677	"Resistor,Chip,MCR03EZPJ391 390OHM"
R517	0RJ1002D677	"Resistor,Chip,MCR03EZPJ103 10KOHM"
R518	0RJ1000D677	"Resistor,Chip,MCR03EZPJ101 100OHM"
R519	0RJ1502D677	"Resistor,Chip,MCR03EZPJ153 15KOHM"
R520	0RJ0000D677	"Resistor,Chip,MCR03EZPJ000 0OHM 5%"
R521	0RJ0000D677	"Resistor,Chip,MCR03EZPJ000 0OHM 5%"
R522	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R523	0RJ1000D677	"Resistor,Chip,MCR03EZPJ101 100OHM"
R524	0RJ1002D677	"Resistor,Chip,MCR03EZPJ103 10KOHM"
R525	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R526	0RJ0332D677	"Resistor,Chip,MCR03EZPJ330 33OHM 5"
R527	0RJ0332D677	"Resistor,Chip,MCR03EZPJ330 33OHM 5"
R530	0RJ1002D677	"Resistor,Chip,MCR03EZPJ103 10KOHM"
R6	0RJ2201D677	"Resistor,Chip,MCR03EZPJ222 2.2KOHM"
R700	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R701	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R702	0RJ0332D677	"Resistor,Chip,MCR03EZPJ330 33OHM 5"
R703	0RJ0102D677	"Resistor,Chip,MCR03EZPJ100 10OHM 5"
R704	0RJ0102D677	"Resistor,Chip,MCR03EZPJ100 10OHM 5"
R705	0RJ0102D677	"Resistor,Chip,MCR03EZPJ100 10OHM 5"
R706	0RJ0102D677	"Resistor,Chip,MCR03EZPJ100 10OHM 5"
R707	0RJ0102D677	"Resistor,Chip,MCR03EZPJ100 10OHM 5"
R708	0RJ0102D677	"Resistor,Chip,MCR03EZPJ100 10OHM 5"
R709	0RJ0332D677	"Resistor,Chip,MCR03EZPJ330 33OHM 5"
R711	0RJ0102D677	"Resistor,Chip,MCR03EZPJ100 10OHM 5"
R712	0RJ0102D677	"Resistor,Chip,MCR03EZPJ100 10OHM 5"
R713	0RJ1001D677	"Resistor,Chip,MCR03EZPJ102 1KOHM 5"
R715	0RJ0332D677	"Resistor,Chip,MCR03EZPJ330 33OHM 5"
R716	0RJ0752D677	"Resistor,Chip,MCR03EZPJ750 75OHM 5"
R717	0RJ0682D677	"Resistor,Chip,MCR03EZPJ680 68OHM 5"
R718	0RJ0682D677	"Resistor,Chip,MCR03EZPJ680 68OHM 5"
R719	0RJ0332D677	"Resistor,Chip,MCR03EZPJ330 33OHM 5"
R720	0RJ0752D677	"Resistor,Chip,MCR03EZPJ750 75OHM 5"
R721	0RJ0752D677	"Resistor,Chip,MCR03EZPJ750 75OHM 5"
R723	0RJ3601D677	"Resistor,Chip,MCR03EZPJ362 3.6KOHM"
R725	0RJ1002D677	"Resistor,Chip,MCR03EZPJ103 10KOHM"
R726	0RJ3900D677	"Resistor,Chip,MCR03EZPJ391 390OHM"
R727	0RJ1002D677	"Resistor,Chip,MCR03EZPJ103 10KOHM"
R728	0RJ3900D677	"Resistor,Chip,MCR03EZPJ391 390OHM"
R729	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R730	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R731	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R734	0RX0331K668	"Resistor,Metal Oxide Film,RSD02F4J3R30 3.3OHM"
R735	0RH1002D622	"Resistor,Chip,MCR10EZPJ103 10KOHM"
R749	0RJ2001D677	"Resistor,Chip,MCR03EZPJ202 2KOHM 5"
R750	0RJ2700D677	"Resistor,Chip,MCR03EZPJ271 270OHM"
R751	0RJ2700D677	"Resistor,Chip,MCR03EZPJ271 270OHM"
R752	0RJ1000D677	"Resistor,Chip,MCR03EZPJ101 100OHM"
R753	0RJ1000D677	"Resistor,Chip,MCR03EZPJ101 100OHM"
R754	0RJ0000D677	"Resistor,Chip,MCR03EZPJ000 0OHM 5%"
R755	0RJ1001D677	"Resistor,Chip,MCR03EZPJ102 1KOHM 5"
R758	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"

LOC NO.	PART NO.	DESCRIPTION/SPECIFICATON
R759	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R760	0RJ2001D677	"Resistor,Chip,MCR03EZPJ202 2KOHM 5"
R761	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R762	0RJ4701D677	"Resistor,Chip,MCR03EZPJ472 4.7KOHM"
R766	0RJ1002D677	"Resistor,Chip,MCR03EZPJ103 10KOHM"
R767	0RJ1001D677	"Resistor,Chip,MCR03EZPJ102 1KOHM 5"
R768	0RJ1000D677	"Resistor,Chip,MCR03EZPJ101 100OHM"
R769	0RJ0000D677	"Resistor,Chip,MCR03EZPJ000 0OHM 5%"
R773	0RJ2001D677	"Resistor,Chip,MCR03EZPJ202 2KOHM 5"
R8	0RJ2701D677	"Resistor,Chip,MCR03EZPJ272 2.7KOHM"
CONNECTORS		
P1	6602T12005E	"Connector,Wafer,12505WR-06A00 6P 1.2"
P2	6602T12005C	"Connector,Wafer,12505WR-04A00 4P 1.2"
P3	6602T12005C	"Connector,Wafer,12505WR-04A00 4P 1.2"
P700	6630TGA005B	"Connector,DSUB,QH11121-DN0-D DVI 24"
P701	6630G100316	"Connector,DSUB,DZ11AA1-HVG-PF D-SUB"
P702	6630V90220E	"Connector,Wafer,TJC2004-6A 6P 2.0MM"
P704	6630V90220K	"Connector,Wafer,TJC2004-11A 11P 2.0M"
P705	EAG37060101	"Connector,FFC/FPC/PIC,10031HR-30 30P 1.00M"
SWITCHES		
SW1	EBF37991701	"Switch,Tact,KMB-903/TMB-901 1C1P"
SW2	EBF37991701	"Switch,Tact,KMB-903/TMB-901 1C1P"
SW3	EBF37991701	"Switch,Tact,KMB-903/TMB-901 1C1P"
SW4	EBF37991701	"Switch,Tact,KMB-903/TMB-901 1C1P"
SW5	EBF37991701	"Switch,Tact,KMB-903/TMB-901 1C1P"
SW6	EBF37991701	"Switch,Tact,KMB-903/TMB-901 1C1P"
SW7	6600R000133	"Switch,Tact,JTP1280A6 1C1P 12VDC"
OTHERS		
LD2	0DLGP0128AA	"LED,Chip,GPTD1210YBC BLUE/YEL"
X501	6212AA2001G	"Crystal,HLX-U-F-14.31818M-18"

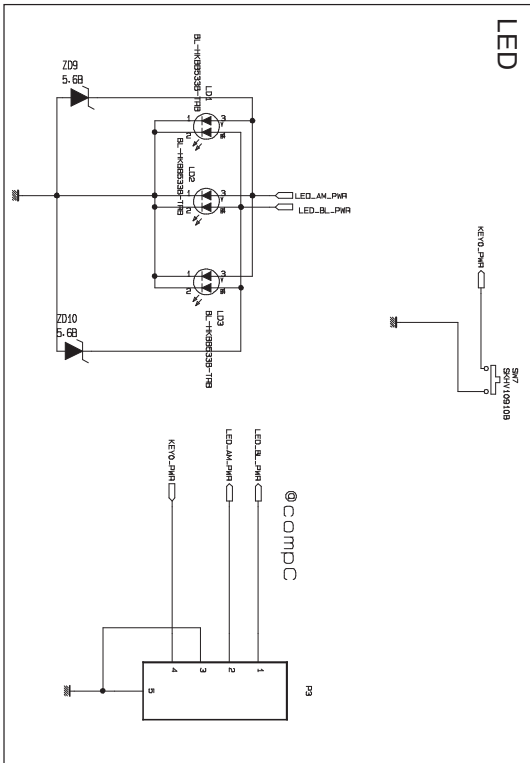
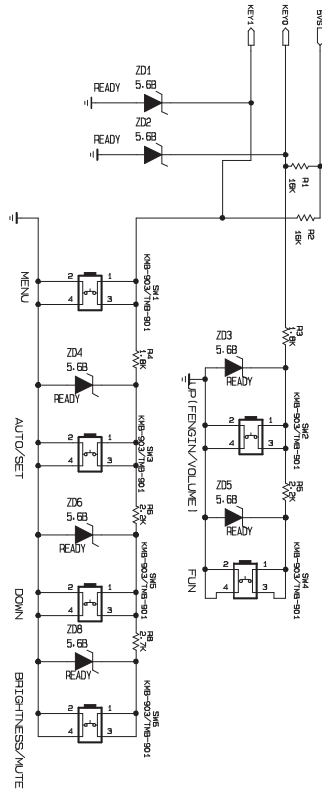
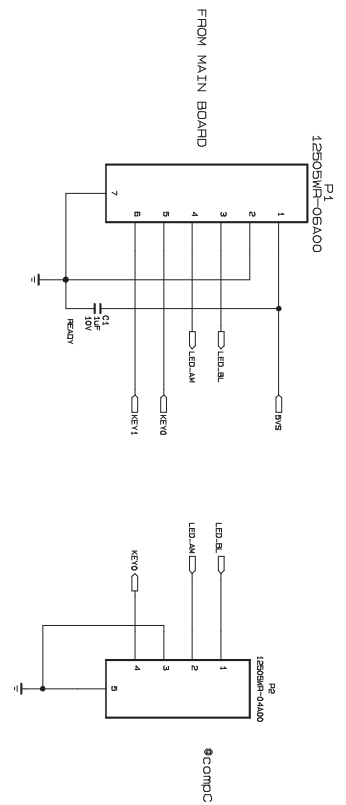
1. SCALER



2. POWER & WAFER



3. CONTROL





P/NO : MFL30290856

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